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# FDP047AN08A0 / FDH047AN08A0

## N-Channel PowerTrench® MOSFET

75 V, 80 A, 4.7 mΩ

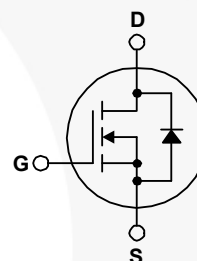
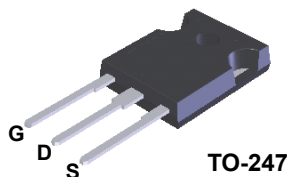
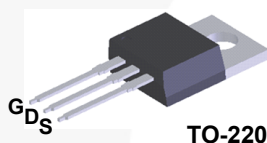
### Features

- $R_{DS(ON)} = 4.0 \text{ m}\Omega$  (Typ.),  $V_{GS} = 10 \text{ V}$ ,  $I_D = 80 \text{ A}$
- $Q_g(\text{tot}) = 92 \text{ nC}$  (Typ.),  $V_{GS} = 10 \text{ V}$
- Low Miller Charge
- Low  $Q_{rr}$ , Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)

### Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies

Formerly developmental type 82684



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FDP047AN08A0 FDH047AN08A0	Unit
$V_{DSS}$	Drain to Source Voltage	75	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current		
	Continuous ( $T_C < 144^\circ\text{C}$ , $V_{GS} = 10\text{V}$ )	80	A
	Continuous ( $T_C = 25^\circ\text{C}$ , $V_{GS} = 10\text{V}$ , with $R_{\theta JA} = 62^\circ\text{C/W}$ )	15	A
	Pulsed	Figure 4	A
$E_{AS}$	Single Pulse Avalanche Energy (Note 1)	475	mJ
$P_D$	Power dissipation	310	W
	Derate above $25^\circ\text{C}$	2.0	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature	-55 to 175	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case, Max. TO-220, TO-247	0.48	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient, Max. TO-220 (Note 2)	62	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient, Max. TO-247 (Note 2)	30	$^\circ\text{C/W}$

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP047AN08A0	FDP047AN08A0	TO-220	Tube	N/A	50 units
FDH047AN08A0	FDH047AN08A0	TO-247	Tube	N/A	30 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
--------	-----------	-----------------	-----	-----	-----	------

### Off Characteristics

$B_{VDSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	75	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}$ $V_{GS} = 0\text{V}$ $T_C = 150^\circ\text{C}$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2	-	4	V
$r_{DS(ON)}$	Drain to Source On Resistance	$I_D = 80\text{A}, V_{GS} = 10\text{V}$	-	0.0040	0.0047	$\Omega$
		$I_D = 37\text{A}, V_{GS} = 6\text{V}$	-	0.0058	0.0087	
		$I_D = 80\text{A}, V_{GS} = 10\text{V},$ $T_J = 175^\circ\text{C}$	-	0.0082	0.011	

### Dynamic Characteristics

$C_{ISS}$	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$	-	6600	-	pF
$C_{OSS}$	Output Capacitance		-	1000	-	pF
$C_{RSS}$	Reverse Transfer Capacitance		-	240	-	pF
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0\text{V to } 10\text{V}$	-	92	138	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0\text{V to } 2\text{V}$	-	11	17	nC
$Q_{gs}$	Gate to Source Gate Charge	$V_{DD} = 40\text{V}$ $I_D = 80\text{A}$ $I_g = 1.0\text{mA}$	-	27	-	nC
$Q_{gs2}$	Gate Charge Threshold to Plateau		-	16	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	21	-	nC

### Switching Characteristics ( $V_{GS} = 10\text{V}$ )

$t_{ON}$	Turn-On Time	$V_{DD} = 40\text{V}, I_D = 80\text{A}$ $V_{GS} = 10\text{V}, R_{GS} = 3.3\Omega$	-	-	160	ns
$t_{d(ON)}$	Turn-On Delay Time		-	18	-	ns
$t_r$	Rise Time		-	88	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time		-	40	-	ns
$t_f$	Fall Time		-	45	-	ns
$t_{OFF}$	Turn-Off Time		-	-	128	ns

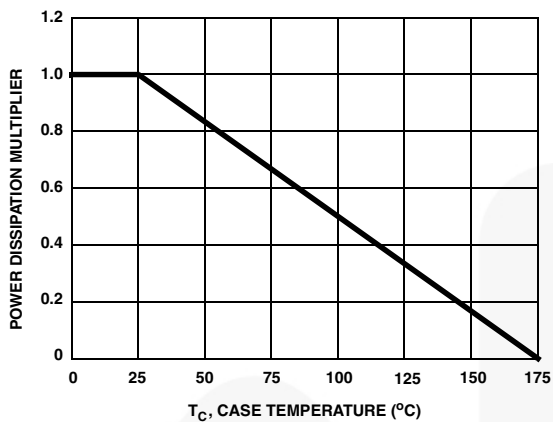
### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Voltage	$I_{SD} = 80\text{A}$	-	-	1.25	V
		$I_{SD} = 40\text{A}$	-	-	1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 75\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	53	ns
$Q_{RR}$	Reverse Recovered Charge	$I_{SD} = 75\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	54	nC

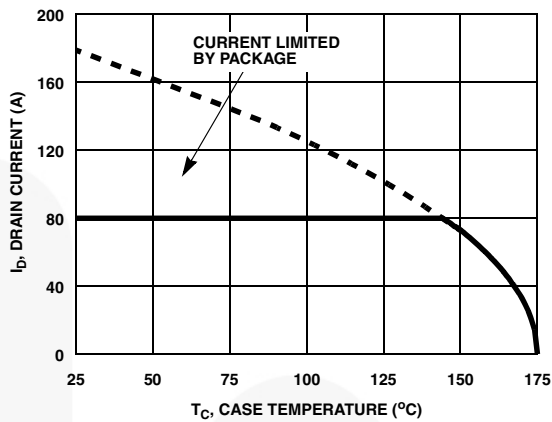
#### Notes:

- Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.232\text{mH}$ ,  $I_{AS} = 64\text{A}$ .
- Pulse Width = 100s

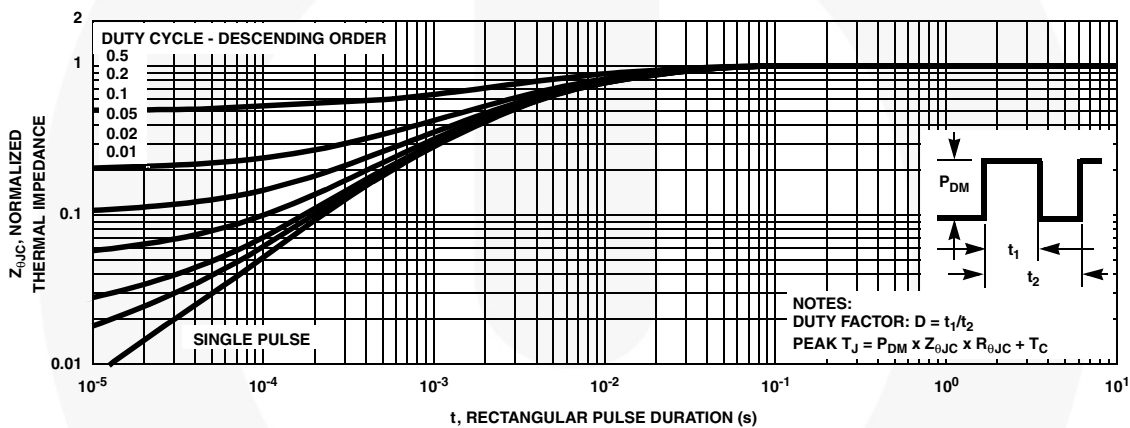
**Typical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted



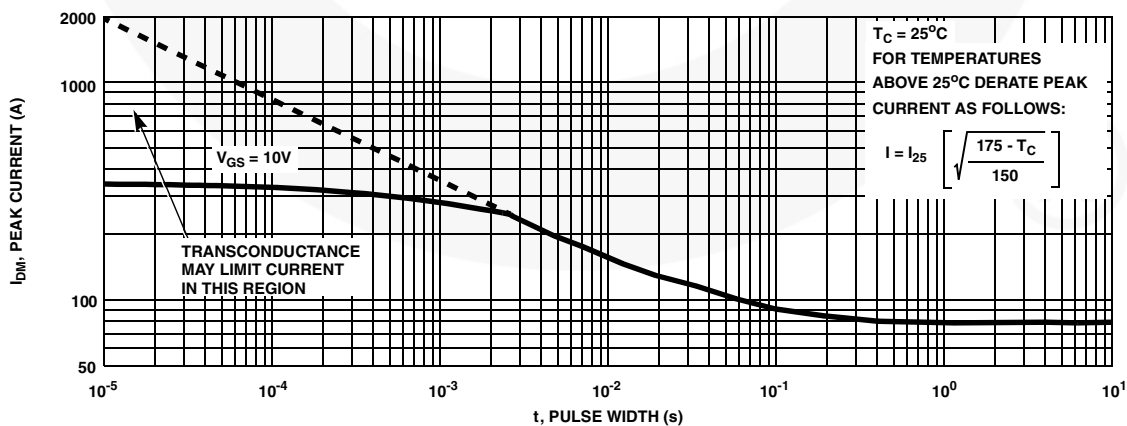
**Figure 1. Normalized Power Dissipation vs Case Temperature**



**Figure 2. Maximum Continuous Drain Current vs Case Temperature**

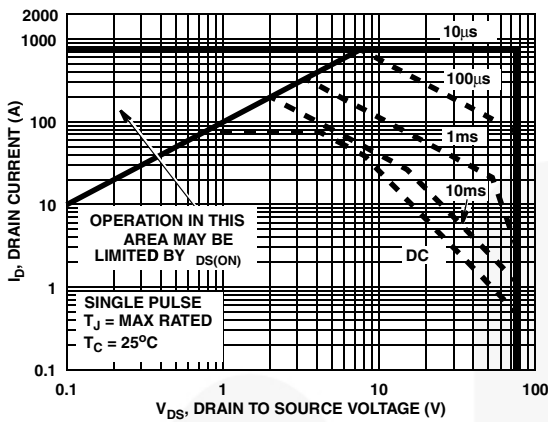


**Figure 3. Normalized Maximum Transient Thermal Impedance**

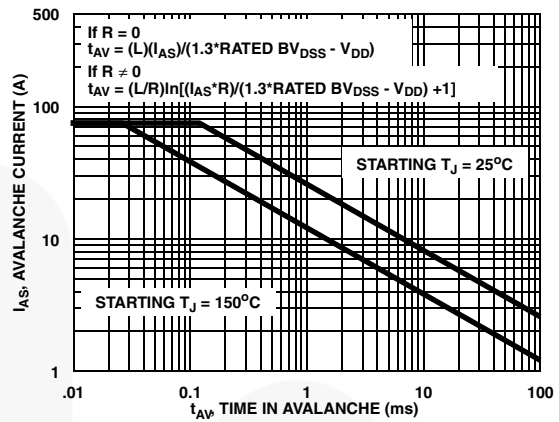


**Figure 4. Peak Current Capability**

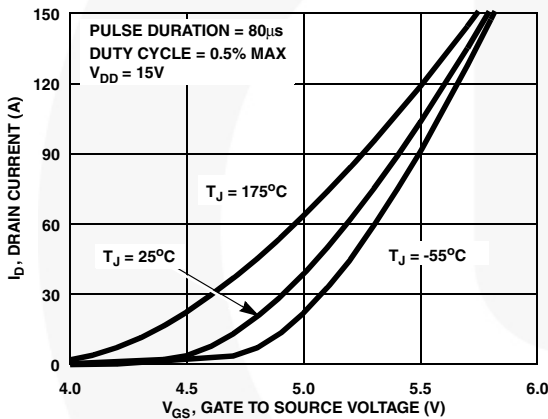
**Typical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted



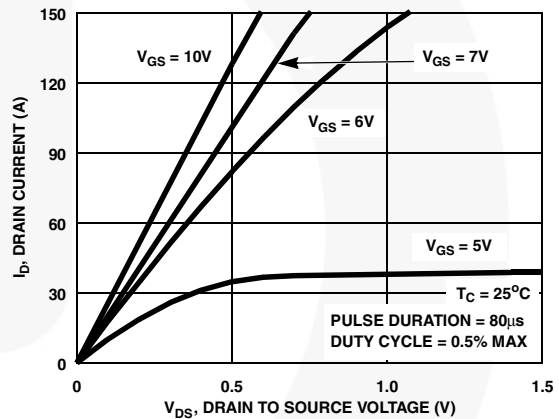
**Figure 5. Forward Bias Safe Operating Area**



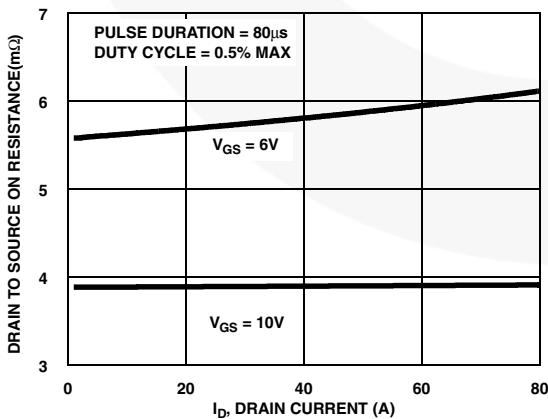
**Figure 6. Unclamped Inductive Switching Capability**  
NOTE: Refer to Fairchild Application Notes AN7514 and AN7515



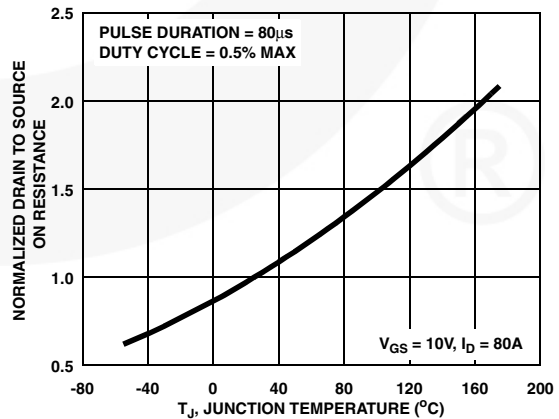
**Figure 7. Transfer Characteristics**



**Figure 8. Saturation Characteristics**

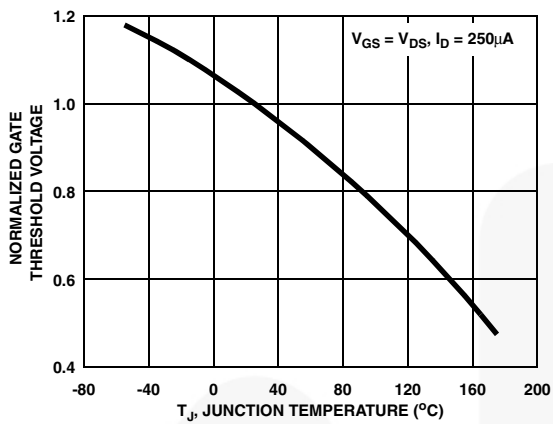


**Figure 9. Drain to Source On Resistance vs Drain Current**

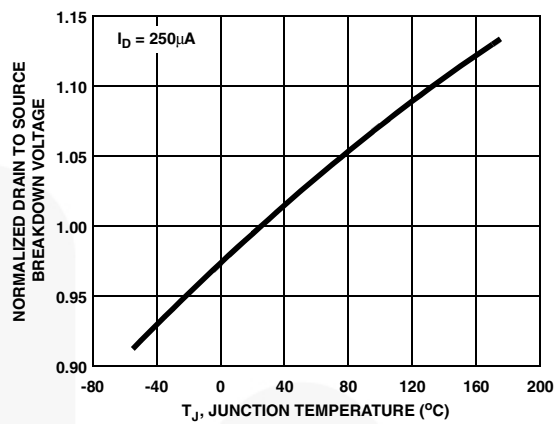


**Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature**

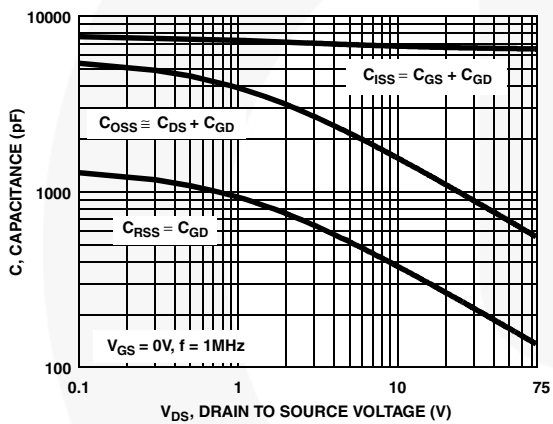
**Typical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted



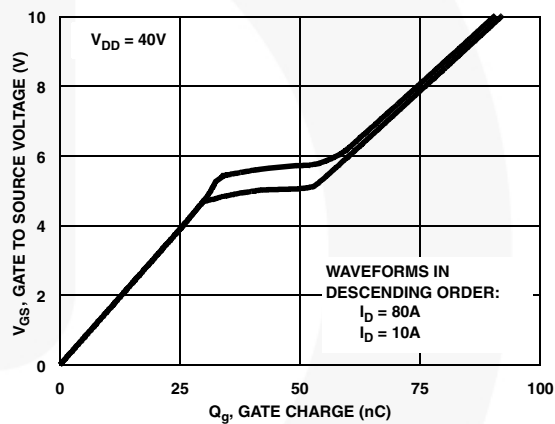
**Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature**



**Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature**



**Figure 13. Capacitance vs Drain to Source Voltage**



**Figure 14. Gate Charge Waveforms for Constant Gate Currents**

### Test Circuits and Waveforms

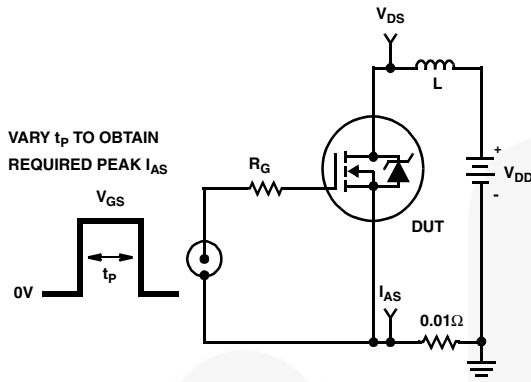


Figure 15. Unclamped Energy Test Circuit

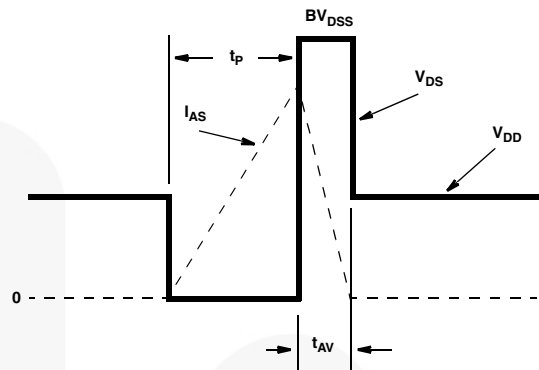


Figure 16. Unclamped Energy Waveforms

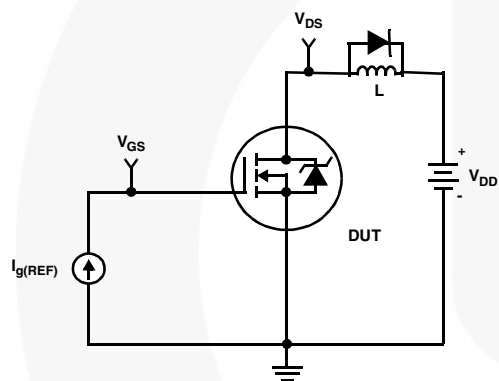


Figure 17. Gate Charge Test Circuit

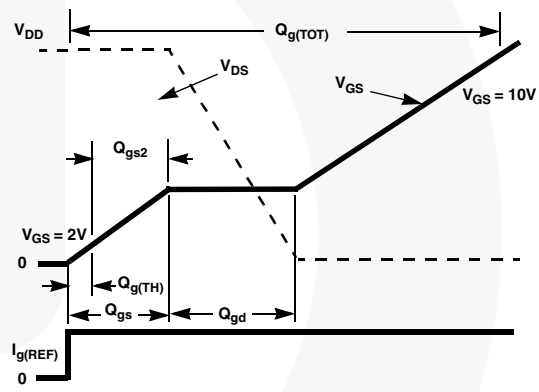


Figure 18. Gate Charge Waveforms

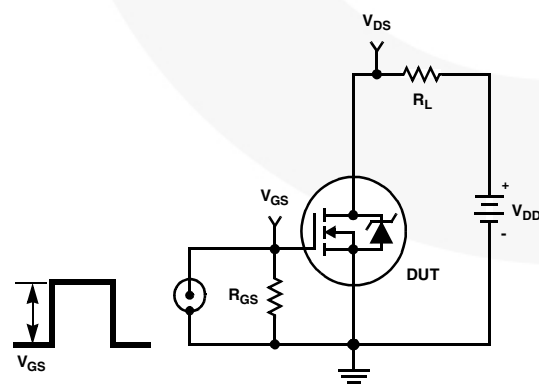


Figure 19. Switching Time Test Circuit

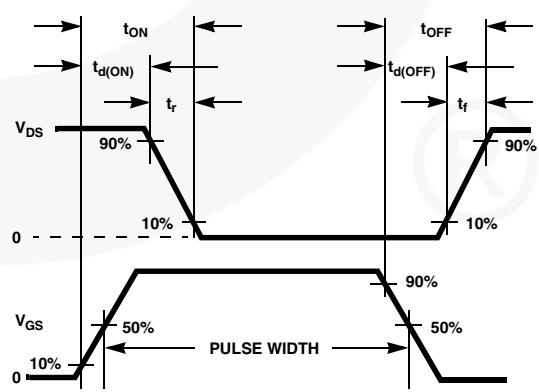


Figure 20. Switching Time Waveforms

### PSPICE Electrical Model

.SUBCKT FDP047AN08A0 2 1 3 ; rev March 2002  
 CA 12 8 1.5e-9  
 CB 15 14 1.5e-9  
 CIN 6 8 6.4e-9

DBODY 7 5 DBODYMOD  
 DBREAK 5 11 DBREAKMOD  
 DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 82.3  
 EDS 14 8 5 8 1  
 EGS 13 8 6 8 1  
 ESG 6 10 6 8 1  
 EVTHRES 6 21 19 8 1  
 EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1e-9  
 LGATE 1 9 4.81e-9  
 LSOURCE 3 7 4.63e-9

MMED 16 6 8 8 MMEDMOD  
 MSTRO 16 6 8 8 MSTROMOD  
 MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1  
 RDRAIN 50 16 RDRAINMOD 9e-4  
 RGATE 9 20 1.36  
 RLDRAIN 2 5 10  
 RLGATE 1 9 48.1  
 RLSOURCE 3 7 46.3  
 RSLC1 5 51 RSLCMOD 1e-6  
 RSLC2 5 50 1e3  
 RSOURCE 8 7 RSOURCEMOD 2.3e-3  
 RVTHRES 22 8 RVTHRESMOD 1  
 RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD  
 S1B 13 12 13 8 S1BMOD  
 S2A 6 15 14 13 S2AMOD  
 S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

ESLC 51 50 VALUE={{(V(5,51)/ABS(V(5,51)))^(PWR(V(5,51))/(1e-6\*250),10))}}

.MODEL DBODYMOD D (IS = 2.4e-11 N = 1.04 RS = 1.76e-3 TRS1 = 2.7e-3 TRS2 = 2e-7 XTI = 3.9 CJO = 4.35e-9 TT = 1e-8 M = 5.4e-1)

.MODEL DBREAKMOD D (RS = 1.5e-1 TRS1 = 1e-3 TRS2 = -8.9e-6)

.MODEL DPLCAPMOD D (CJO = 1.35e-9 IS = 1e-30 N = 10 M = 0.53)

.MODEL MMEDMOD NMOS (VTO = 3.7 KP = 9 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 1.36)

.MODEL MSTROMOD NMOS (VTO = 4.4 KP = 250 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)

.MODEL MWEAKMOD NMOS (VTO = 3.05 KP = 0.03 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 1.36e1 RS = 0.1)

.MODEL RBREAKMOD RES (TC1 = 1.05e-3 TC2 = -9e-7)

.MODEL RDRAINMOD RES (TC1 = 1.9e-2 TC2 = 4e-5)

.MODEL RSLCMOD RES (TC1 = 1.3e-3 TC2 = 1e-5)

.MODEL RSOURCEMOD RES (TC1 = 1e-3 TC2 = 1e-6)

.MODEL RVTHRESMOD RES (TC1 = -6e-3 TC2 = -1.9e-5)

.MODEL RVTEMPMOD RES (TC1 = -2.4e-3 TC2 = 1e-6)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.0 VOFF = -1.5)

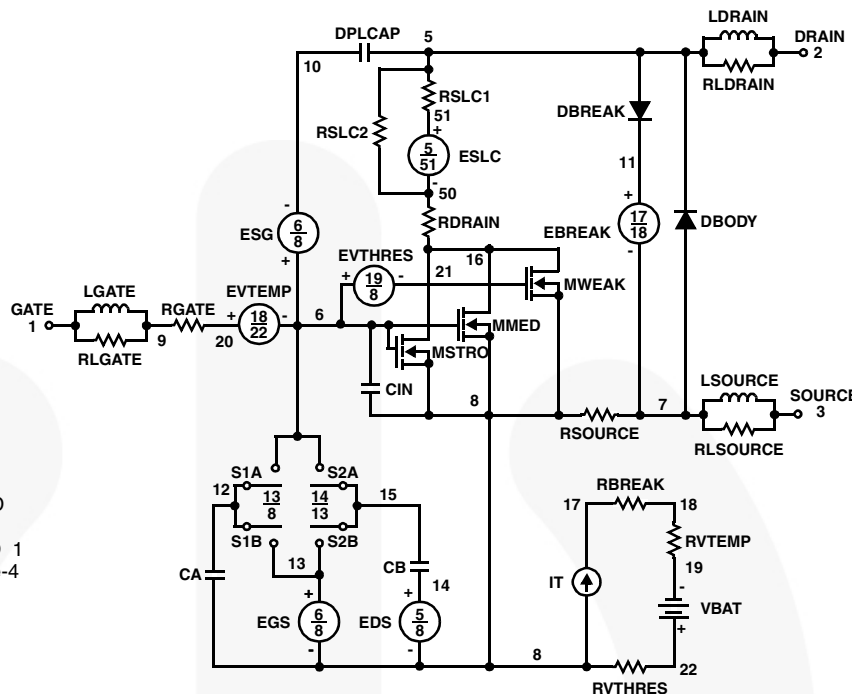
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.5 VOFF = -4.0)

.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.0 VOFF = 0.5)

.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.5 VOFF = -1.0)

.ENDS

Note: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.





### SABER Electrical Model

REV March 2002

template FDP047AN08A0 n2,n1,n3

electrical n2,n1,n3

```

{
var i iscl
dp..model dbodymod = (isl = 2.4e-11, n1 = 1.04, rs = 1.76e-3, trs1 = 2.7e-3, trs2 = 2e-7, xti = 3.9, cjo = 4.35e-9, tt = 1e-8, m = 5.4e-1)
dp..model dbreakmod = (rs = 1.5e-1, trs1 = 1e-3, trs2 = -8.9e-6)
dp..model dplcapmod = (cjo = 1.35e-9, isl = 10e-30, nl = 10, m = 0.53)
m..model mmedmod = (type=_n, vto = 3.7, kp = 9, is = 1e-30, tox=1)
m..model mstrongmod = (type=_n, vto = 4.4, kp = 250, is = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 3.05, kp = 0.03, is = 1e-30, tox = 1, rs=0.1)
sw_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -4.0, voff = -1.5)
sw_vcsp..model s1bmod = (ron = 1e-5, roff = 0.1, von = -1.5, voff = -4.0)
sw_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.0, voff = 0.5)
sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.0)

```

```

c.ca n12 n8 = 1.5e-9
c.cb n15 n14 = 1.5e-9
c.cin n6 n8 = 6.4e-9

```

```

dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod

```

```
i.it n8 n17 = 1
```

```

l.l drain n2 n5 = 1e-9
l.l gate n1 n9 = 4.81e-9
l.l source n3 n7 = 4.63e-9

```

```

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

```

```

res.rbreak n17 n18 = 1, tc1 = 1.05e-3, tc2 = -9e-7
res.rdrain n50 n16 = 9e-4, tc1 = 1.9e-2, tc2 = 4e-5
res.rgate n9 n20 = 1.36
res.rldrain n2 n5 = 10
res.rlgate n1 n9 = 48.1
res.rlsource n3 n7 = 46.3
res.rslc1 n5 n51 = 1e-6, tc1 = 1e-3, tc2 = 1e-5
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 2.3e-3, tc1 = 1e-3, tc2 = 1e-6
res.rvtemp n18 n19 = 1, tc1 = -2.4e-3, tc2 = 1e-6
res.rvthres n22 n8 = 1, tc1 = -6e-3, tc2 = -1.9e-5

```

```

spe.ebreak n11 n7 n17 n18 = 82.3
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1

```

```

sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

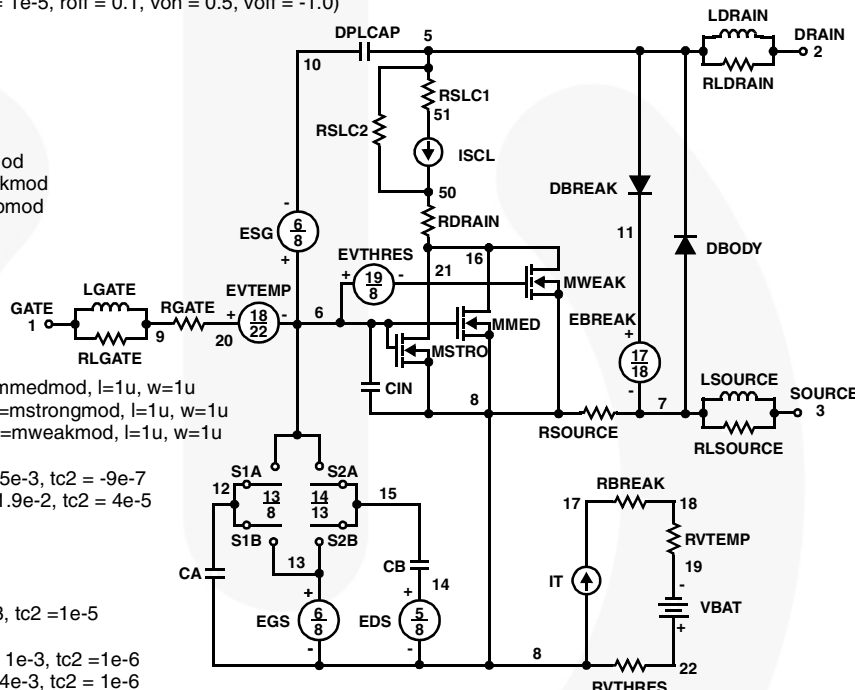
```

```
v.vbat n22 n19 = dc=1
```

```

equations {
i (n51->n50) += iscl
iscl: v(n51,n50) = (((v(n5,n51))/(1e-9+abs(v(n5,n51)))))*((abs(v(n5,n51))*1e6/250)** 10))
}
}

```



### SPICE Thermal Model

REV 23 March 2002

FDP047AN08A0T

```

CTHERM1 th 6 6.45e-3
CTHERM2 6 5 3e-2
CTHERM3 5 4 1.4e-2
CTHERM4 4 3 1.65e-2
CTHERM5 3 2 4.85e-2
CTHERM6 2 tl 1e-1
    
```

```

R THERM1 th 6 3.24e-3
R THERM2 6 5 8.08e-3
R THERM3 5 4 2.28e-2
R THERM4 4 3 1e-1
R THERM5 3 2 1.1e-1
R THERM6 2 tl 1.4e-1
    
```

### SABER Thermal Model

SABER thermal model FDP047AN08A0T

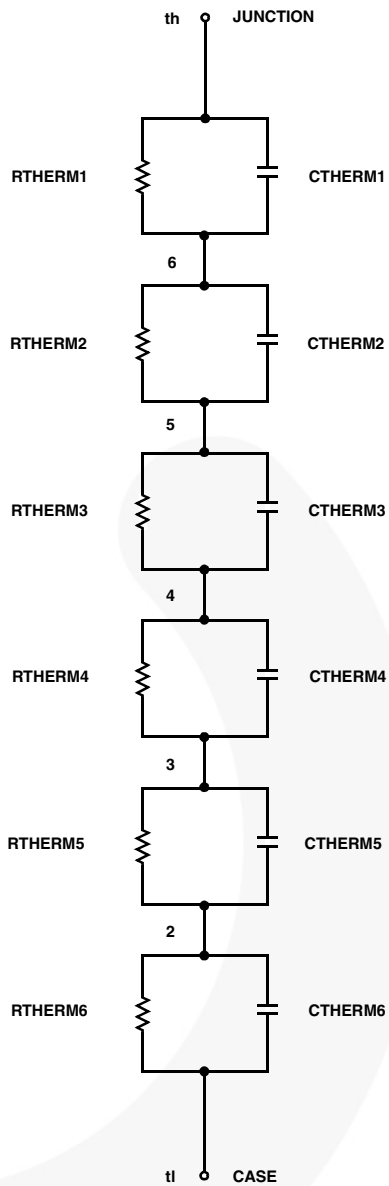
template thermal\_model th tl  
thermal\_c th, tl

```

{
ctherm.ctherm1 th 6 = 6.45e-3
ctherm.ctherm2 6 5 = 3e-2
ctherm.ctherm3 5 4 = 1.4e-2
ctherm.ctherm4 4 3 = 1.65e-2
ctherm.ctherm5 3 2 = 4.85e-2
ctherm.ctherm6 2 tl = 1e-1
    
```

```

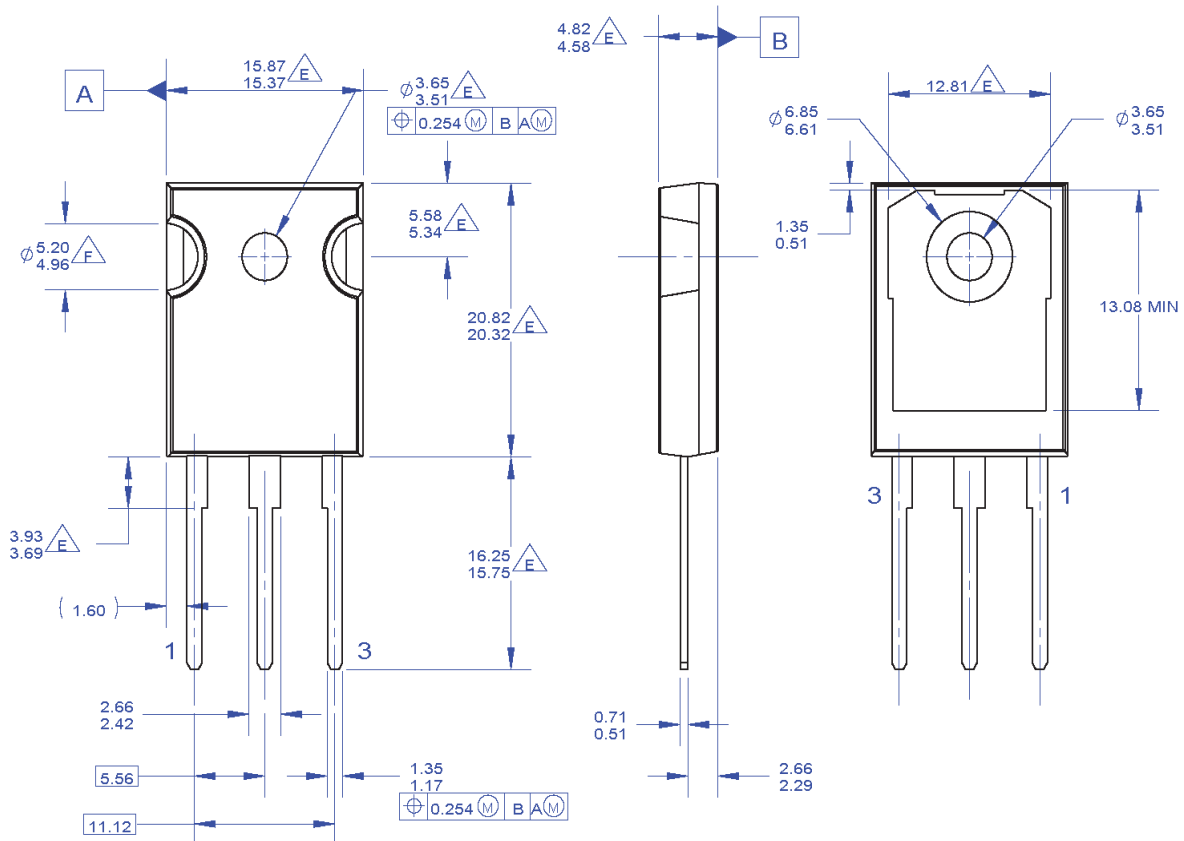
rtherm.rtherm1 th 6 = 3.24e-3
rtherm.rtherm2 6 5 = 8.08e-3
rtherm.rtherm3 5 4 = 2.28e-2
rtherm.rtherm4 4 3 = 1e-1
rtherm.rtherm5 3 2 = 1.1e-1
rtherm.rtherm6 2 tl = 1.4e-1
}
    
```





## Mechanical Dimensions

### TO-247 3L



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 - 1994

$\triangle E$  DOES NOT COMPLY JEDEC STANDARD VALUE

$\triangle F$  NOTCH MAY BE SQUARE

G. DRAWING FILENAME: MKT-TO247A03\_REV03

**Figure 22. TO-247, Molded, 3 Lead, Jedec Variation AB**

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Dimension in Millimeters



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